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ched original documents or copy thereof.

1. Name of conveying party(ies):

Tsutomu Nosu
Keiko Katsuki

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: Kyowa Chemical Industry Co., Ltd.

Internal Address: _____

300 Rec'd PCT/PTO 04 MAR 1999

Street Address: 305, Yashimanishimachi,
Takamatsu-shi, Kagawa-ken, 761-0113 Japan

City: _____ State: _____ ZIP: _____

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Execution Date: February 23, 1999

4. Application number(s) or patent number(s):

09,254,258

If this document is being filed together with a new application, the execution date of the application is: February 23, 1999

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Leonard W. Sherman
Internal Address: SHERMAN AND SHALLOWAY

Street Address: 413 N. Washington Street

City: Alexandria State: VA ZIP: 22314

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41).....\$ 40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit account number:

19-1980

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Leonard W. Sherman
Name of Person Signing

Signature

March 4, 1999

Date

2

Total number of pages including cover sheet, attachments, and document:

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents & Trademarks, Box Assignments **PATENT**

Washington, D.C. 20231

REEL: 010010 FRAME: 0548

ASSIGNMENT

WHEREAS, We, Tsutomu NOSU and Keiko KATSUKI

residing at Sakaide-shi, Kagawa-ken, Japan, respectively

(hereinafter referred to as Inventors), have invented certain new and useful improvements in SYNTHETIC RESIN COMPOSITION HAVING HEAT DETERIORATION RESISTANCE AND MOLDED ARTICLE THEREOF;

for which an application for United States Letters Patent was signed by us on February 23, 1999 and filed in the United States on _____ and assigned Serial Number _____.

WHEREAS, KYOWA CHEMICAL INDUSTRY CO., LTD. a corporation of Japan, having a place of business at 305, Yashimanishimachi, Takamatsu-shi, Kagawa-ken 761-0113 JAPAN (hereinafter referred to as Company), is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefor in the United States and in any and all foreign countries.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, the receipt whereof is hereby acknowledged, and other valuable considerations, the said Inventors have sold, assigned and transferred, and by the presents do sell, assign and transfer unto said Company, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent, which may be granted thereof in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations and extensions thereof.

We hereby authorize and request the Patent Office Officials in the United States and in any and all foreign countries to issue any and all of said Letters Patent, when granted, to said Company as the assignee of the entire right, title and interest in and to the same, for the sole use and behoof of the said Company, its successors and assigns.

FURTHER, We agree that we will communicate to said Company or its representatives any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitution, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said Company, make all rightful oaths and generally do everything possible to aid said Company, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

IN TESTIMONY WHEREOF, We have hereunto set our hands this 23th day of February, 1999.

Signed in the presence of:

Witness: Genro Fieki

Signed: Tsutomu Nosu

Witness: _____

Signed: Keiko Katsuki

Witness: _____

Signed: _____

Witness: _____

Signed: _____

Witness: _____

Signed: _____

Witness: _____

Signed: _____